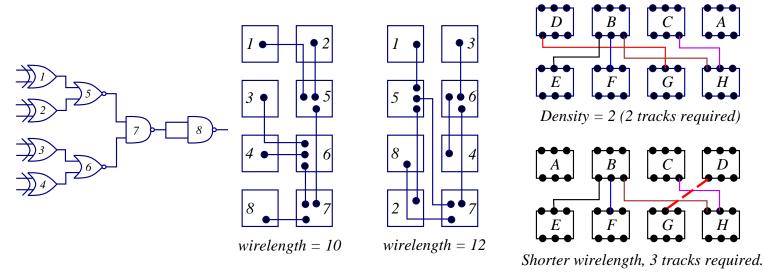
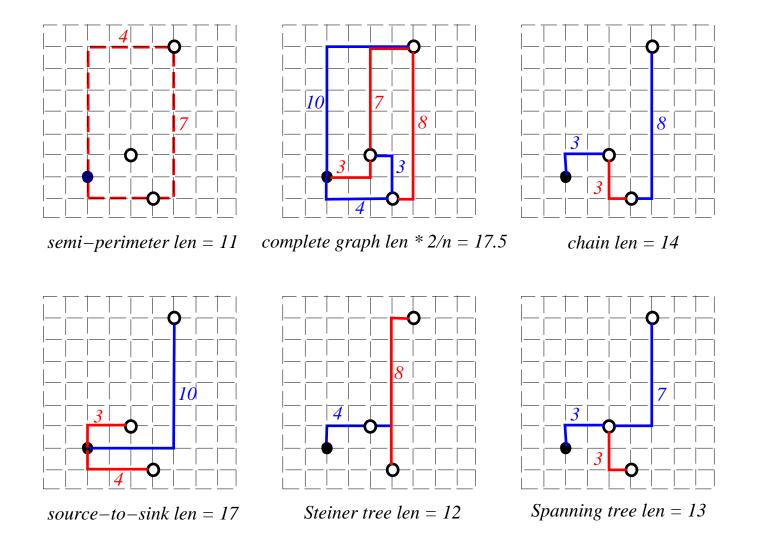
Placement

- The process of arranging the circuit components on a layout surface.
- Inputs: A set of fixed modules, a netlist.
- Goal: Find the best position for each module on the chip according to appropriate cost functions.
 - Considerations: routability/channel density, wirelength, cut size, performance, thermal issues, I/O pads.



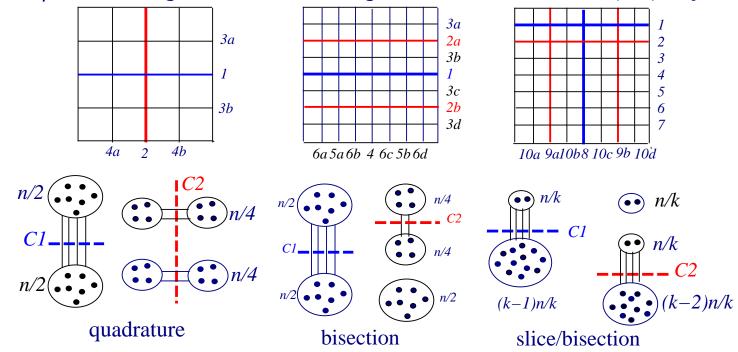
Estimation of Wirelength

- **Semi-perimeter method:** Half the perimeter of the bounding rectangle that encloses all the pins of the net to be connected. Most widely used approximation!
- Complete graph: Since #edges in a complete graph $(\frac{n(n-1)}{2})$ is $\frac{n}{2} \times \#$ of tree edges (n-1), $wirelength \approx \frac{2}{n} \sum_{(i,j) \in net} dist(i,j)$.
- Minimum chain: Start from one vertex and connect to the closest one, and then to the next closest, etc.
- Source-to-sink connection: Connect one pin to all other pins of the net. Not accurate for uncongested chips.
- Steiner-tree approximation: Computationally expensive.
- Minimum spanning tree



Min-Cut Placement

- Breuer, "A class of min-cut placement algorithms," DAC-77.
- Quadrature: suitable for circuits with high density in the center.
- Bisection: good for standard-cell placement.
- Slice/Bisection: good for cells with high interconnection on the periphery.



Algorithm for Min-Cut Placement

```
Algorithm: Min_Cut_Placement(N, n, C)

/* N: the layout surface */

/* n: # of cells to be placed */

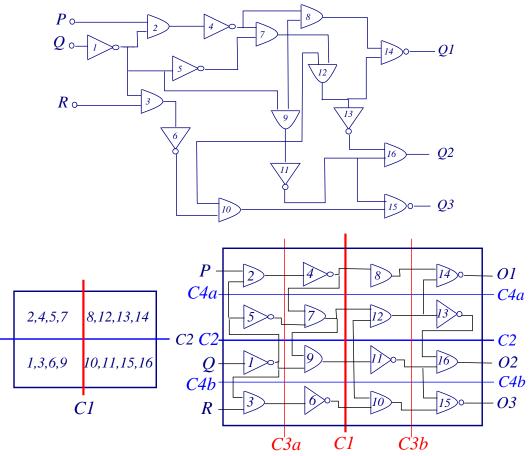
/* n_0: # of cells in a slot */

/* C: the connectivity matrix */

1 begin
2 if (n \le n_0) then PlaceCells(N, n, C);
3 else
4 (N_1, N_2) \leftarrow \text{CutSurface}(N);
5 (n_1, C_1), (n_2, C_2) \leftarrow \text{Partition}(n, C);
6 Call Min_Cut_Placement(N_1, n_1, C_1);
7 Call Min_Cut_Placement(N_2, n_2, C_2);
8 end
```

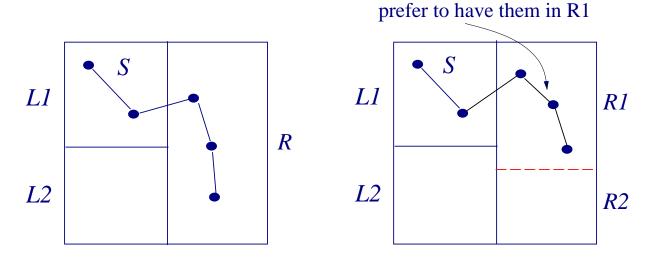
Quadrature Placement Example

• Apply K-L heuristic to partition + Quadrature Placement: Cost $C_1=4$, $C_{2L}=C_{2R}=2$, etc.



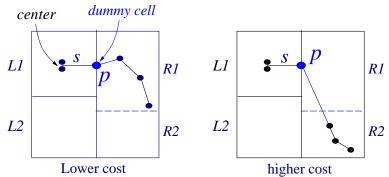
Min-Cut Placement with Terminal Propagation

- Dunlop & Kernighan, "A procedure for placement of standard-cell VLSI circuits," IEEE TCAD, Jan. 1985.
- Drawback of the original min-cut placement: Does not consider the positions of terminal pins that enter a region.
 - What happens if we swap {1, 3, 6, 9} and {2, 4, 5, 7} in the previous example?



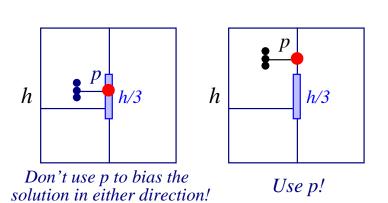
Terminal Propagation

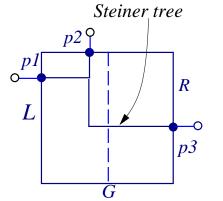
• We should use the fact that s is in L_1 !



P will stay in R1 for the rest of partitioning!

ullet When not to use p to bias partitioning? Net s has cells in many groups?

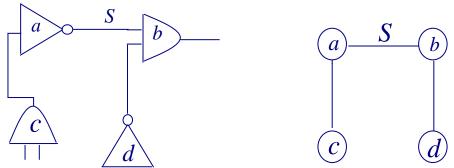


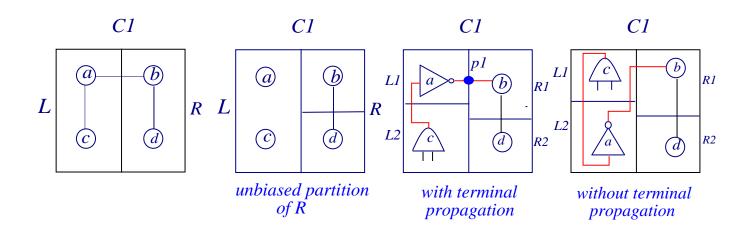


minimum rectilinear

Terminal Propagation Example

• Partitioning must be done breadth-first, not depth-first.



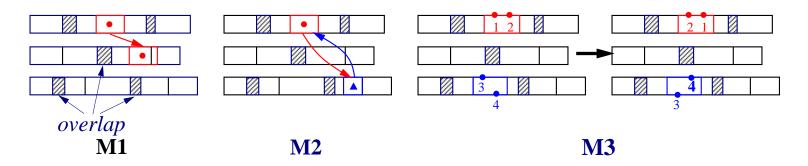


Placement by Simulated Annealing

- Sechen and Sangiovanni-Vincentelli, "The TimberWolf placement and routing package," IEEE J. Solid-State Circuits, Feb. 1985; "TimberWolf 3.2: A new standard cell placement and global routing package," DAC-86.
- TimberWolf: Stage 1
 - Modules are moved between different rows as well as within the same row.
 - Modules overlaps are allowed.
 - When the temperature is reached below a certain value, stage 2 begins.
- TimberWolf: Stage 2
 - Remove overlaps.
 - Annealing process continues, but only interchanges adjacent modules within the same row.

Solution Space & Neighborhood Structure

- **Solution Space:** All possible arrangements of the modules into rows, possibly with overlaps.
- Neighborhood Structure: 3 types of moves
 - M_1 : Displace a module to a new location.
 - $-M_2$: Interchange two modules.
 - $-M_3$: Change the orientation of a module.

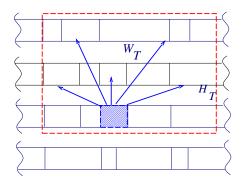


Neighborhood Structure

- TimberWolf first tries to select a move between M_1 and M_2 : $Prob(M_1) = 0.8$, $Prob(M_2) = 0.2$.
- If a move of type M_1 is chosen and it is rejected, then a move of type M_3 for the same module will be chosen with probability 0.1.
- Restrictions: (1) what row for a module can be displaced? (2) what pairs of modules can be interchanged?

Key: Range Limiter

- At the beginning, (W_T, H_T) is very large, big enough to contain the whole chip.
- Window size shrinks slowly as the temperature decreases. Height and width $\propto log(T)$.
- Stage 2 begins when window size is so small that no inter-row module interchanges are possible.



Cost Function

- Cost function: $C = C_1 + C_2 + C_3$.
- C_1 : total estimated wirelength.
 - $C_1 = \sum_{i \in Nets} (\alpha_i w_i + \beta_i h_i)$
 - α_i, β_i are horizontal and vertical weights, respectively. ($\alpha_i = 1, \beta_i = 1 \Rightarrow \frac{1}{2} \times$ perimeter of the bounding box of Net i.)
 - Critical nets: Increase both α_i and β_i .
 - If vertical wirings are "cheaper" than horizontal wirings, use smaller vertical weights: $\beta_i < \alpha_i$.
- C_2 : penalty function for module overlaps.
 - $C_2 = \gamma \sum_{i \neq j} O_{ij}^2$, γ : penalty weight.
 - O_{ij} : amount of overlaps in the x-dimension between modules i and j.
- C_3 : penalty function that controls the row length.
 - $C_2 = \delta \sum_{r \in Rows} |L_r D_r|$, δ : penalty weight.
 - D_r : desired row length.
 - L_r : sum of the widths of the modules in row r.

Annealing Schedule

- $T_k = r_k T_{k-1}, k = 1, 2, 3, \dots$
- \bullet r_k increases from 0.8 to max value 0.94 and then decreases to 0.8.
- ullet At each temperature, a total # of nP attempts is made. n: # of modules; P: user specified constant.
- Termination: T < 0.1.